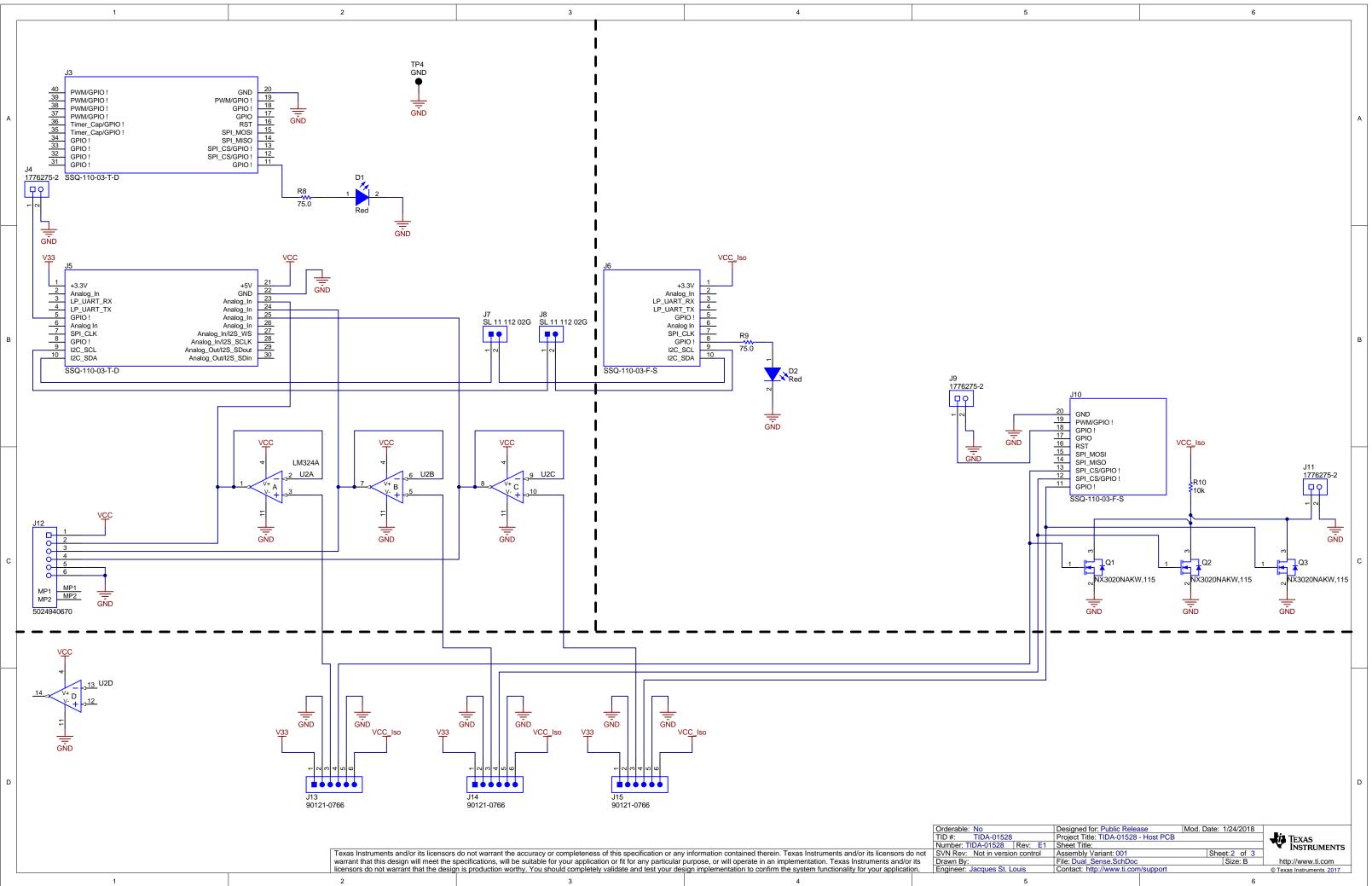


5				6		
Revision History						
Rev	ECN #	Approved Date	Approved by	Notes		
N/A	N/A	N/A	N/A	N/A		



	Designed for: Public Relea	ise	Mod. Da	ate:	10/18/2017	_
28	Project Title: TIDA-01528 ·	- Host PCB				<b>JIA</b> TEXAS
Rev: E1	Sheet Title:					
sion control	Assembly Variant: 001			Shee	et:1 of 3	In torrectine interview
	File: CoverSheet.SchDoc				Size: B	http://www.ti.com
Louis	Contact: http://www.ti.com	support				© Texas Instruments 2017
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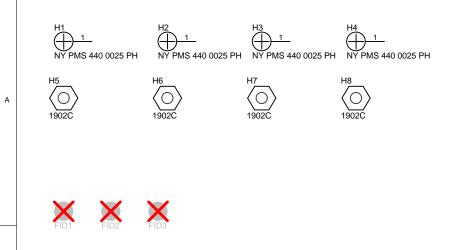


1	2	3	4	5	6		
A							A
	22µŀ	U1 LBOOST VREF_SAMP VREF_SAMP VSTO 2 VIN_DC VB C4 C5 C4 C5 C4 C5 C5 C5 C4 C5 C5 C5 C5 C5 C5 C5 C5 C5 C5	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	TP3 GND		_	
в	4. GND Vbatt OVP at 5.33V R3 4.7I	Image: Second	10µH	GND			В
C	GND Vbatt_ok_prog=1.83 Vbatt_ok_hyst=2.05	R7 ₹6.8M ₹7.5M					с
						_	
D 1	Texas Instruments and/or its licensors warrant that this design will meet the s licensors do not warrant that the design 2	rs do not warrant the accuracy or completeness of this specification or an specifications, will be suitable for your application or fit for any particula ign is production worthy. You should completely validate and test your de 3	any information contained therein. Texas Instruments and/or its licensors do no ar purpose, or will operate in an implementation. Texas Instruments and/or its design implementation to confirm the system functionality for your application.	Number TIDA-01528   Rev: E1		TEXAS INSTRUMENTS http://www.ti.com © Texas Instruments 2017	D



	1	2	2	4	5	6
A	1	2	3	4	5	6
В			VCC Iso	VCC	VCC VCC_Iso	
			C1 0.1µF	R1 10k R2 10k ehm	Fingers for Connector (PN: 65801-006LF)	
С				GND		
D						
	1	Texas Instruments and/or its licensors do not warrant th warrant that this design will meet the specifications, wil licensors do not warrant that the design is production w 2	he accuracy or completeness of this specification or any Il be suitable for your application or fit for any particular vorthy. You should completely validate and test your des 3	y information contained therein. Texas Instruments and/or its licensors do purpose, or will operate in an implementation. Texas Instruments and/or sign implementation to confirm the system functionality for your application 4	Orderable:         No         Designed for: Public Rele           TID #:         TIDA-01528         Project Title:         TIDA-01528           Number:         TIDA-01528         Rev:         E1         Sheet Title:         On ot           SVN Rev:         Not in version control         Assembly Variant: 001         On ot         Trawn By:         File: Main.SchDoc           on.         Engineer:         Jacques St. Louis         Contact:         http://www.ti.cor	ase Mod. Date: 2/8/2018 - Sensor Flex PCB Sheet: 2 of 3 Size: B http://www.ti.com m/support © Texas Instruments 2017 6

1	2	3	4	5	6



PCB Number: TIDA-01528	PCB	PCB	PCB
PCB Rev: E1	LOGO	LOGO	LOGO

Variant/Label Table Label Text

ChangeMe!

ChangeMe!

Variant 001

002

LBL1
PCB Label
Size: 0.65" x 0.20 "
771
<u>ZZ1</u>

ZZ1 Label Assembly Note This Assembly Note is for PCB labels only

1

в

С

D

ZZ2 Assembly Note This Assembly Note will show in the PcbDoc and associated outputs

ZZ3
<u>Assembly Note</u>
This Assembly Note will show in the PcbDoc and associated outputs

ZZ4 Assembly Note This Assembly Note will show in the PcbDoc and associated outputs

			Orderable:	No	Designed for: Public Release	se Mod. Date: 2/8/2018	_
			TID #:	TIDA-01528	Project Title: TIDA-01528 -	Host PCB	Texas
					Sheet Title:		<b>INSTRUMENTS</b>
Texas Instruments and/or its licensors	do not warrant the accuracy or completeness of this specification or any	r information contained therein. Texas Instruments and/or its licensors do no	t SVN Rev:	Not in version control	Assembly Variant: 001	Sheet: 3 of 3	
warrant that this design will meet the s	pecifications, will be suitable for your application or fit for any particular	purpose, or will operate in an implementation. Texas Instruments and/or its	Drawn By:		File: EVM_Hardware.SchD	oc Size: B	http://www.ti.com
licensors do not warrant that the design	n is production worthy. You should completely validate and test your dea	sign implementation to confirm the system functionality for your application.	Engineer:	Jacques St. Louis	Contact: http://www.ti.com	/support	© Texas Instruments 2017
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